

## Diode

Rapid Switching Emitter Controlled Diode

## IDV15E65D2

FullPAK with Emitter Controlled Diode

Data sheet

Industrial Power Control

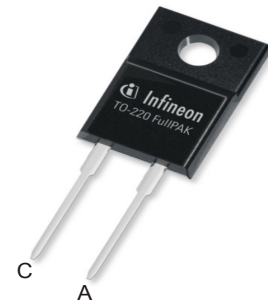
## Rapid Switching Emitter Controlled Diode

### Features:

- Electrically isolated FullPAK for efficient assembly
- 650 V Emitter Controlled technology
- Fast recovery
- Soft switching
- Low reverse recovery charge
- Low forward voltage
- Qualified according to JESD-022 for target applications
- Pb-free lead plating; RoHS compliant
- Halogen free (according to IEC 61249-2-21)
- Complete product spectrum and PSpice Models:  
<http://www.infineon.com/diode/>

### Applications:

- Boost diode in CCM PFC



### Key Performance and Package Parameters

Type	$V_{rrm}$	$I_f$	$V_f, T_{vj}=25^{\circ}\text{C}$	$T_{vjmax}$	Marking	Package
IDV15E65D2	650V	15A	1.6V	175°C	E15ED2	PG-TO220-2-22 FP



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## Emitter Controlled Diode

**Maximum Ratings**

For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

Parameter	Symbol	Value	Unit
Repetitive peak reverse voltage	$V_{RRM}$	650	V
Diode forward current, limited by $T_{vjmax}$ $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	$I_F$	15.0 7.5	A
Diode pulsed current, $t_p$ limited by $T_{vjmax}$	$I_{Fpuls}$	45.0	A
Diode surge non repetitive forward current $T_C = 25^\circ\text{C}$ , $t_p = 8.3\text{ms}$ , sine halfwave	$I_{FSM}$	100.0	A
Power dissipation $T_C = 25^\circ\text{C}$	$P_{tot}$	34.0	W
Operating junction temperature	$T_{vj}$	-40...+175	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55...+150	$^\circ\text{C}$
Soldering temperature, wave soldering 1.6 mm (0.063 in.) from case for 10s		260	$^\circ\text{C}$
Mounting torque, M3 screw Maximum of mounting processes: 3	$M$	0.6	Nm

**Thermal Resistance**

Parameter	Symbol	Conditions	Max. Value	Unit
<b>Characteristic</b>				
Diode thermal resistance, <sup>1)</sup> junction - case	$R_{th(j-c)}$		4.40	K/W
Thermal resistance junction - ambient	$R_{th(j-a)}$		65	K/W

**Electrical Characteristic, at  $T_{vj} = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>Static Characteristic</b>						
Diode forward voltage	$V_F$	$I_F = 15.0\text{A}$ $T_{vj} = 25^\circ\text{C}$ $T_{vj} = 175^\circ\text{C}$	- -	1.60 1.65	2.20 -	V
Reverse leakage current	$I_R$	$V_R = 650\text{V}$ $T_{vj} = 25^\circ\text{C}$ $T_{vj} = 175^\circ\text{C}$	- -	- -	40.0 4000.0	$\mu\text{A}$

**Electrical Characteristic, at  $T_{vj} = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>Dynamic Characteristic</b>						
Internal emitter inductance measured 5mm (0.197 in.) from case	$L_E$		-	7.0	-	nH

<sup>1)</sup> Please be aware that in non standard load conditions, due to high  $R_{th(j-c)}$ ,  $T_{vj}$  close to  $T_{vjmax}$  can be reached.

## Emitter Controlled Diode

## Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	

 Diode Characteristic, at  $T_{vj} = 25^{\circ}\text{C}$ 

Diode reverse recovery time	$t_{rr}$	$T_{vj} = 25^{\circ}\text{C}$ , $V_R = 400\text{V}$ , $I_F = 15.0\text{A}$ , $di_F/dt = 1000\text{A}/\mu\text{s}$ , $L\sigma = 35\text{nH}$ , $C\sigma = 32\text{pF}$ , switch IPW60R045CP	-	30	-	ns
Diode reverse recovery charge	$Q_{rr}$		-	0.20	-	$\mu\text{C}$
Diode peak reverse recovery current	$I_{rrm}$		-	12.8	-	A
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$		-	-6500	-	$\text{A}/\mu\text{s}$
Diode reverse recovery time	$t_{rr}$	$T_{vj} = 25^{\circ}\text{C}$ , $V_R = 400\text{V}$ , $I_F = 15.0\text{A}$ , $di_F/dt = 200\text{A}/\mu\text{s}$ , $L\sigma = 35\text{nH}$ , $C\sigma = 32\text{pF}$ , switch IPW60R045CP	-	47	-	ns
Diode reverse recovery charge	$Q_{rr}$		-	0.12	-	$\mu\text{C}$
Diode peak reverse recovery current	$I_{rrm}$		-	3.3	-	A
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$		-	-1500	-	$\text{A}/\mu\text{s}$

## Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	

 Diode Characteristic, at  $T_{vj} = 175^{\circ}\text{C}/125^{\circ}\text{C}$ 

Diode reverse recovery time	$t_{rr}$	$T_{vj} = 175^{\circ}\text{C}$ , $V_R = 400\text{V}$ , $I_F = 15.0\text{A}$ , $di_F/dt = 1000\text{A}/\mu\text{s}$ , $L\sigma = 35\text{nH}$ , $C\sigma = 32\text{pF}$ , switch IPW60R045CP	-	30	-	ns
Diode reverse recovery charge	$Q_{rr}$		-	0.37	-	$\mu\text{C}$
Diode peak reverse recovery current	$I_{rrm}$		-	16.9	-	A
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$		-	-6800	-	$\text{A}/\mu\text{s}$
Diode reverse recovery time	$t_{rr}$	$T_{vj} = 125^{\circ}\text{C}$ , $V_R = 400\text{V}$ , $I_F = 15.0\text{A}$ , $di_F/dt = 200\text{A}/\mu\text{s}$ , $L\sigma = 35\text{nH}$ , $C\sigma = 32\text{pF}$ , switch IPW60R045CP	-	51	-	ns
Diode reverse recovery charge	$Q_{rr}$		-	0.21	-	$\mu\text{C}$
Diode peak reverse recovery current	$I_{rrm}$		-	5.0	-	A
Diode peak rate of fall of reverse recovery current during $t_b$	$di_{rr}/dt$		-	-1900	-	$\text{A}/\mu\text{s}$

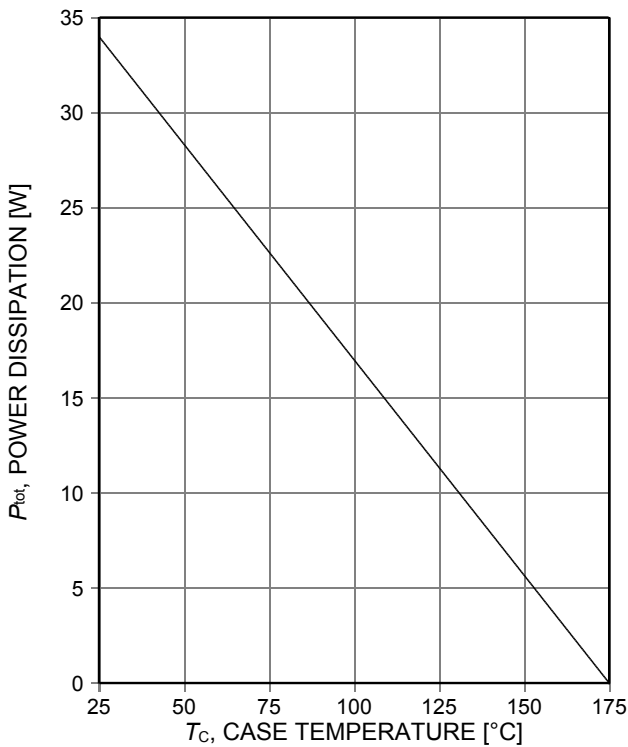


Figure 1. Power dissipation as a function of case temperature ( $T_{vj} \leq 175^\circ\text{C}$ )

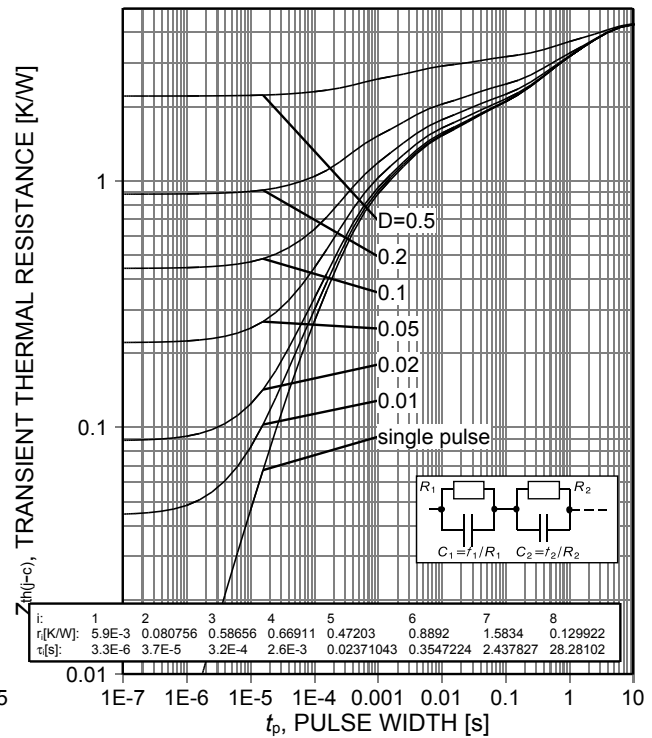


Figure 2. Diode transient thermal impedance as a function of pulse width ( $D = t_p/T$ )

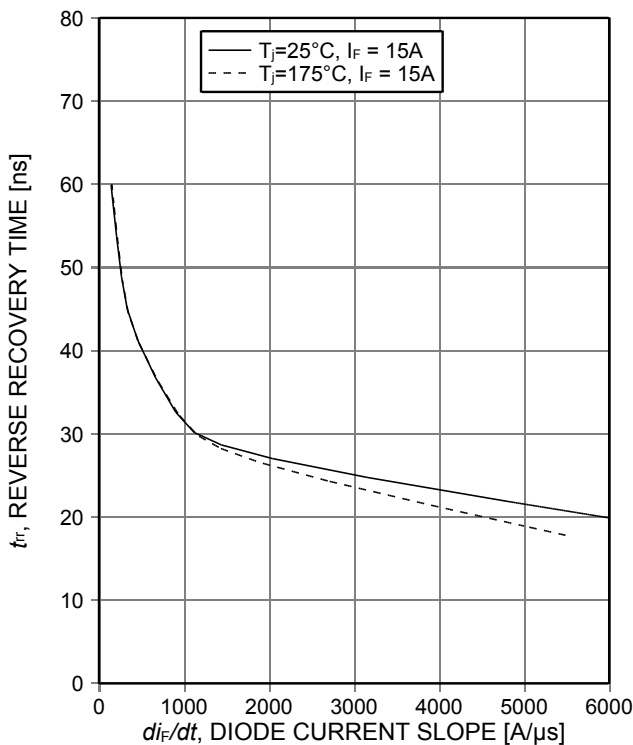


Figure 3. Typical reverse recovery time as a function of diode current slope ( $V_R = 400\text{V}$ )

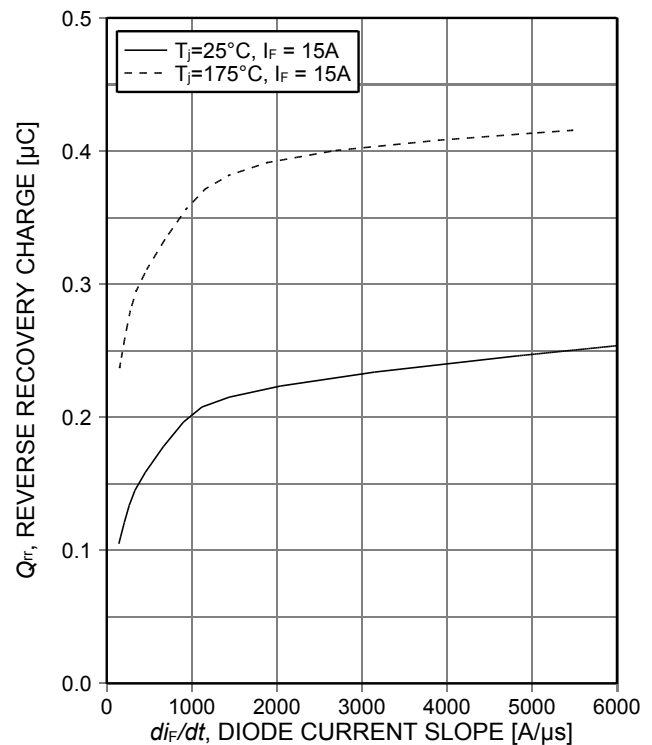


Figure 4. Typical reverse recovery charge as a function of diode current slope ( $V_R = 400\text{V}$ )

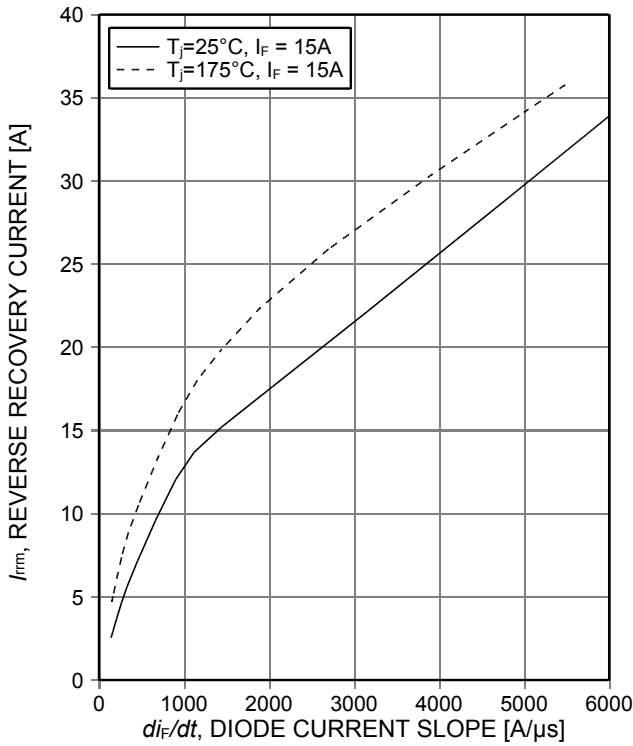


Figure 5. Typical peak reverse recovery current as a function of diode current slope ( $V_R=400V$ )

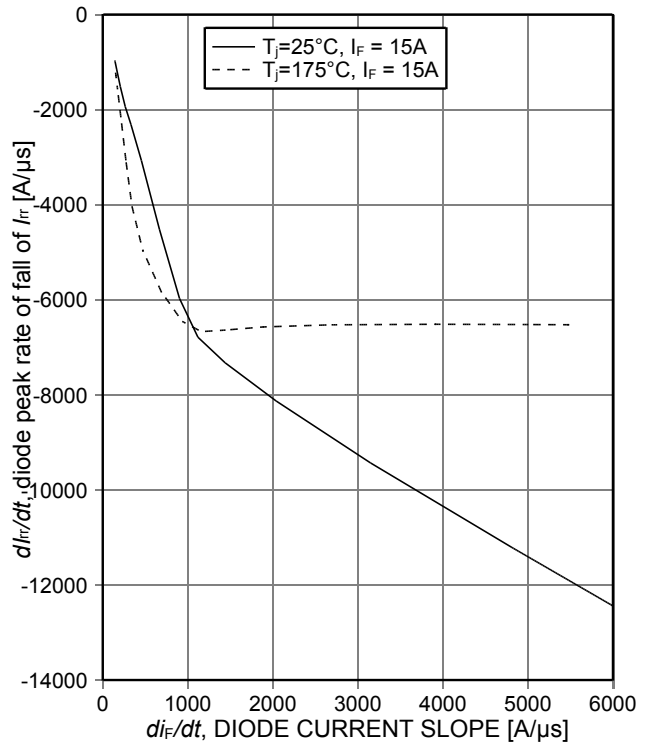


Figure 6. Typical diode peak rate of fall of reverse recovery current as a function of diode current slope ( $V_R=400V$ )

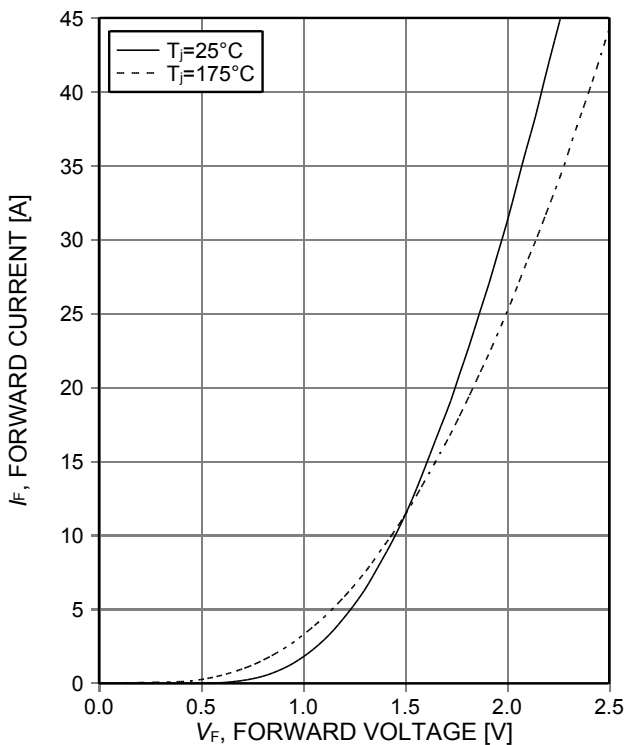


Figure 7. Typical diode forward current as a function of forward voltage

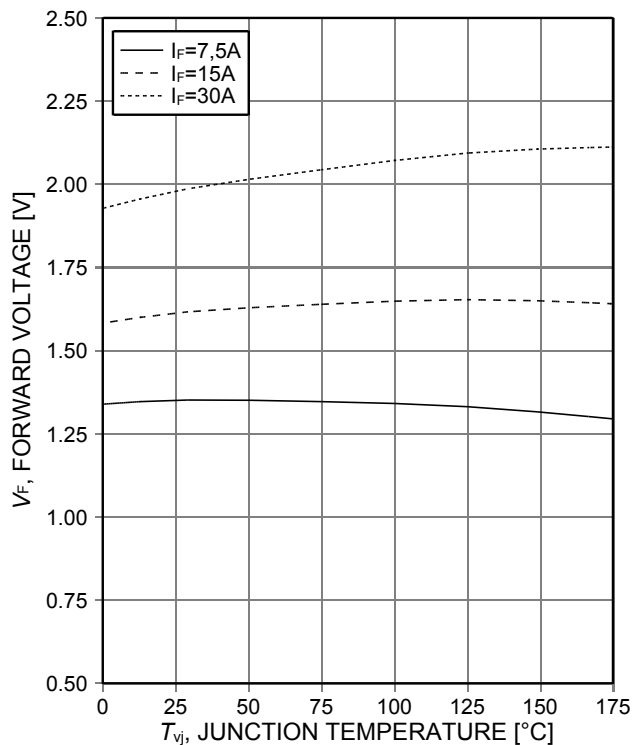


Figure 8. Typical diode forward voltage as a function of junction temperature

Emitter Controlled Diode

PG-TO220-2-22

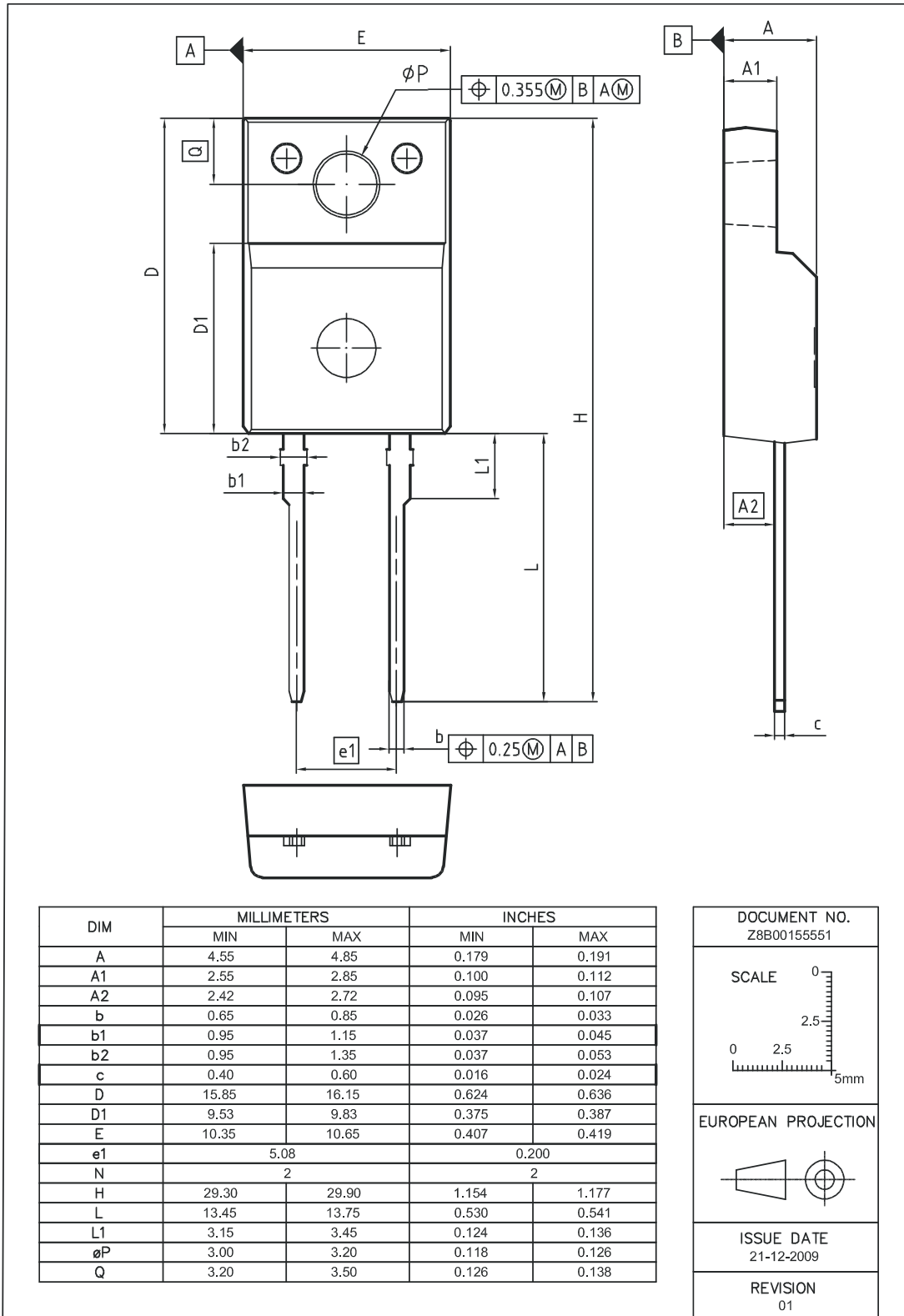






Figure A. Definition of switching times



Figure B. Definition of switching losses

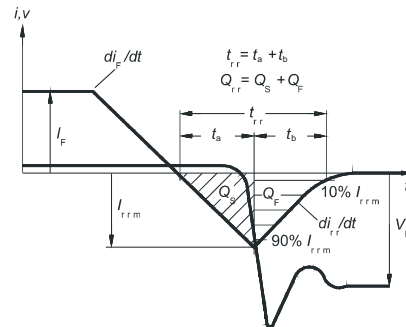


Figure C. Definition of diodes switching characteristics

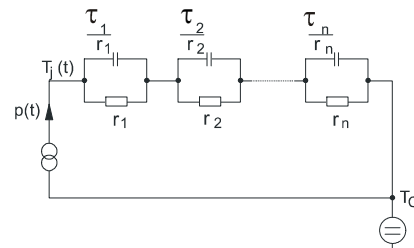


Figure D. Thermal equivalent circuit

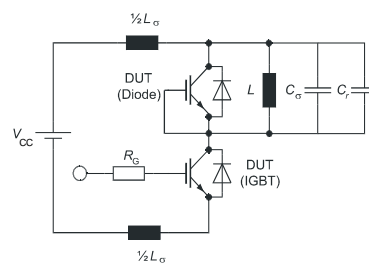


Figure E. Dynamic test circuit  
Parasitic inductance  $L_\sigma$ ,  
Parasitic capacitor  $C_\sigma$ ,  
Relief capacitor  $C_r$   
(only for ZVT switching)

## Revision History

IDV15E65D2

Revision: 2014-08-26, Rev. 2.2

## Previous Revision

Revision	Date	Subjects (major changes since last revision)
1.1	2013-03-13	Preliminary data sheet
2.1	2013-12-16	Final DS / New Marking Pattern
2.2	2014-08-26	VFmax limit reduced according BE test and Qrr at 25°C corrected

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